# Product End-of-Life Disassembly Instructions

## Product Category: Notebooks and Tablet PCs

### Marketing Name / Model
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Model</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP Chromebook 14 G3</td>
</tr>
</tbody>
</table>

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>
Components and waste containing asbestos  
Components, parts and materials containing refractory ceramic fibers  
Components, parts and materials containing radioactive substances  

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove base rubber foot rear side -L & -R
2. Remove base screw rubber *3

3. Dis-fasten BASE screw*13
4. Open top case with base cover

5. Pull out Battery cables
6. Pull out Touch Pad FFC cables

7. Pull out Keyboard cables
8. Pull out LCD cables

9. Pull out Antenna cables
10. Dis-fasten Hinge screw*2

11. Separate LCD Module with Base units
12. Pull out DC-in cable

13. Pull out speaker cable
14. Pull out USB FFC cable

15. Dis-fasten Wireless card screw*1
16. Dis-fasten Wireless card

17. Dis-fasten screw*2 (daughter boards screw*2)
18. Dis-fasten screw*12 (Motherboard*4 Battery*8)

19. Remove Battery
20. Remove Motherboards

21. Remove USB board
22. Remove speaker –L & -R

23. Remove bezel screw mylar *2
24. Dis-fasten LCD Bezel screw*2

25. Remove LCD bezel
26. Dis-fasten Hinge screw*8

27. Remove Hinge –L & -R
28. Dis-fasten panel screw *4

29. Pull out LCD LCD cable
30. Remove LCD Module

31. Remove camera module

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

PSG instructions for this template are available at EL-MF877-01
3.22 Remove battery module

3.23 LCD module set disassembly
3.24 Top case disassembly

3.25 Thermal module and mother board disassembly
3.26 Bottom case disassembly